

Claims 13-18 are rejected under 35 U.S.C. § 102 for anticipation based upon Shimada, U.S. Patent No. 5,631,502

On pages two through three of the Office Action, the Examiner asserted that Shimada discloses a method of manufacturing a package for accommodating electronic parts corresponding to that claimed. This rejection is respectfully traversed.

Independent claim 13 recites, in part, forming a buildup substrate having a core substrate and a buildup interconnecting layer. Applicant notes, however, that the Examiner referred to element 101 in Shimada as teaching both of these layers without explaining how a single feature in Shimada can identically disclose two separately claimed features. On this basis alone, Applicant respectfully submits that Shimada fails to identically disclose the claimed invention.

Notwithstanding, there are additional claimed features not disclosed by Shimada. For example, claim 13 recites "a power source and/or ground layer on said core substrate" (emphasis added), and in the statement of the rejection, the Examiner asserted that features 213, 214 respectively disclose the claimed power source and/or ground layer. Upon reviewing Fig. 4 of Shimada, which was referred to by the Examiner in the statement of the rejection, it is apparent that the power/ground layers 213, 214 of Shimada are formed in the multilayer substrate 101 and not on the multilayer substrate 101, as claimed. Thus, Shimada fails to identically disclose a power source and/or ground layer on a core substrate, as recited in claim 13.

Furthermore, Applicant separately argues the patentability of each claim. In this respect, Applicant notes that for all the limitations the Examiner discussed on page three of the Office

Action, the Examiner merely referred to "(Fig. 13)" of Shimada as disclosing these limitations without any additional explanation as to what features in Fig. 13 disclose the claimed limitations. In this regard, the Examiner's rejection under 35 U.S.C. § 103 fails to comply with 37 C.F.R. § 1.104(c).¹ The Examiner has not specifically identified where Shimada teaches the claimed grounding plane (claim 13); fixing a conductive adhesive layer at a ground potential (claim 14); and providing pads connected to the grounding plane on the surface of the buildup substrate as well as electrically connecting the pads to the conductive adhesive layer (claim 16). Furthermore, the Examiner has not explained where Shimada specifically teaches that the Examiner's asserted ground connecting pads 201, 202 in Shimada are connected to the asserted conductive adhesive layer 506 (claims 15 and 17-18). Notwithstanding, these features are neither taught nor suggested by Shimada.

Thus, Shimada fails to identically disclose the claimed invention within the meaning of 35 U.S.C. § 102. Applicant, therefore, respectfully submits that the imposed rejection of claims 13-18 under 35 U.S.C. § 102 for anticipation based upon Shimada is not factually viable and, hence, solicits withdrawal thereof.

Applicant has made every effort to present claims which distinguish over the prior art, and it is believed that all claims are in condition for allowance. However, Applicant invites the

¹ 37 C.F.R. § 1.104(c) provides:

In rejecting claims for want of novelty or for obviousness, the examiner must cite the best references at his or her command. When a reference is complex or shows or describes inventions other than that claimed by the applicant, the particular part relied on must be designated as nearly as practicable. The pertinence of each reference, if not apparent, must be clearly explained and each rejected claim specified.

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Examiner to call the undersigned if it is believed that a telephonic interview would expedite the prosecution of the application to an allowance. Accordingly, and in view of the foregoing remarks, Applicant hereby respectfully requests reconsideration and prompt allowance of the pending claims.

To the extent necessary, a petition for an extension of time under 37 C.F.R. § 1.136 is hereby made. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

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A handwritten signature in black ink, appearing to read 'Scott D. Paul', written over a horizontal line.

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